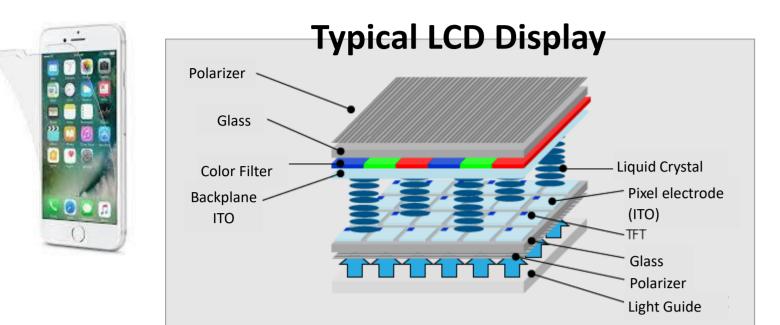
# Deterioration mechanism of RF-sputtered ITO film on plastic substrates



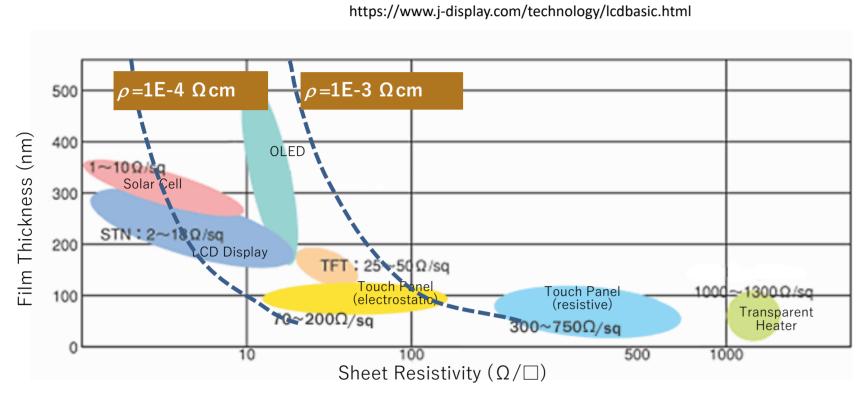
# Tsuneo FUKUDA, Masahiro TAGUCHI, Takayoshi SHINGU Graduate School of Engineering, Osaka City University - OSAKA (Japan)

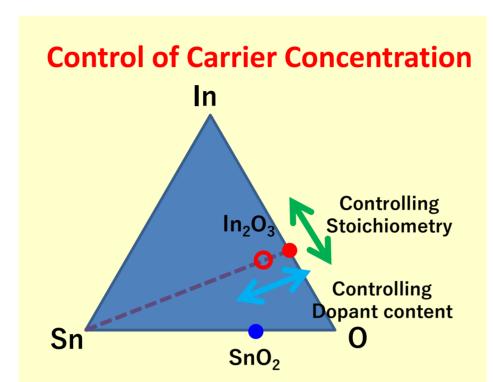
#### Introduction

Forming thin films on flexible substrates such as polymer films is an important technical issue for manufacturing lightweight portable electronic devices. In particular, a transparent conductive film such as indium tin oxide (ITO) is indispensable technologies for liquid crystal displays as shown in Figures. Therefore, ITO film formation on flexible substrates that can be bent while maintaining low resistance and high optical transmittance is essential for the development of future portable display devices. However, research on the durability of such flexible transparent conductive films has only just begun, and there are many unclear problems regarding the mechanism of deterioration of electrical properties.



ltem	Sheet Resistivity (Ω/□)	Bulk Resistivity $ ho\left(\Omega\mathrm{cm} ight)$	Transparenc y (%)	Material
Display (LCD/OLED)	2-20	<4E-4	>80	ITO
Display (Touch Panel)	100-1 k	<1E-2	>93	ITO
Solar Cell	1-10	<4E-4	>80 (with texture)	SnO <sub>2</sub> :F AZO
Anti Reflecting	N. R.	N. R.	Depending on application	ITO, SnO <sub>2</sub> TiO <sub>2</sub> etc.





### Research Objective

- Forming a low resistance transparent conductive film on plastic substrates
- Evaluation of durability of transparent conductive film and clarify the deterioration mechanism

#### **TCO Growth Condition**

Substrate: Polyethylene naphthalate (PEN),

Teijin-DuPont Teonex QA65HA 125μm (Tg=155°C)

Growth Method: RF-magnetron sputtering

**Growth Conditions:** 

Target:  $In_2O_3:SnO_2=90:10 (3'')$ 

Power: 0.9W/cm<sup>2</sup>

Sample-Target distance: 62 mm Sputtering Gas: Ar+H<sub>2</sub> (O<sub>2</sub>) Film thickness: nom. 100 nm Typical growth rate: 22 nm/min.

Sample temp. during film growth: Room Temperature (water cooled)

### **Evaluation**

Film Thickness: Dektak 3030ST

Surface Morphology: AFM SII SPI-3800N

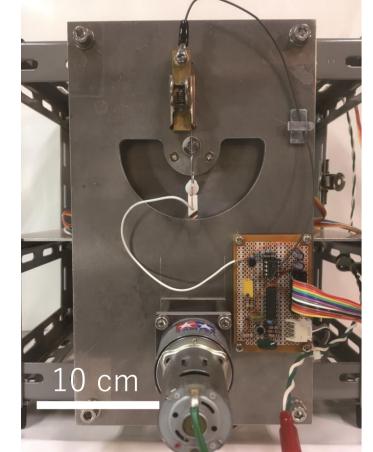
Carrier Mobility and Concentration: 4-terminal Van der Pauw (under  $\pm$  1.0 T)

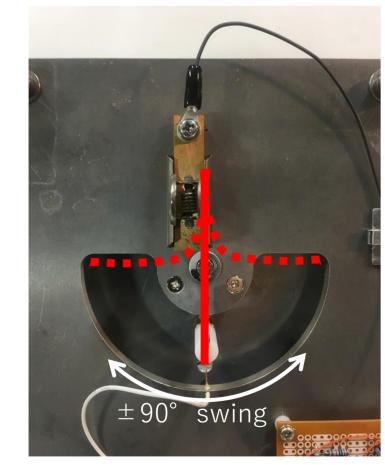
Optical transmittance: Home- made spectrophotometer

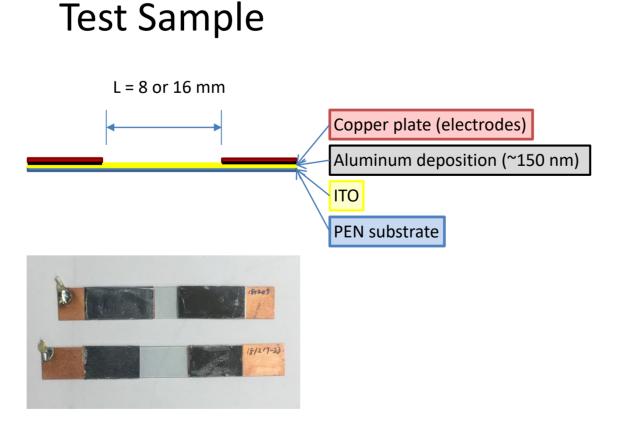
Crystallinity: XRD ( $\theta$ –2 $\theta$ )

Durability: Home-made bending test equipment (In situ resistivity measurement possible)

### Bending Tester

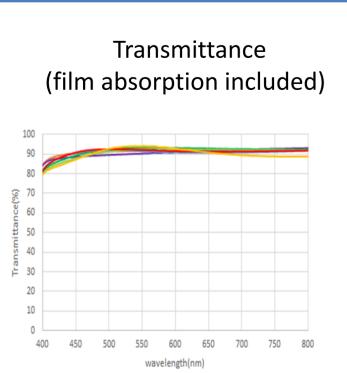


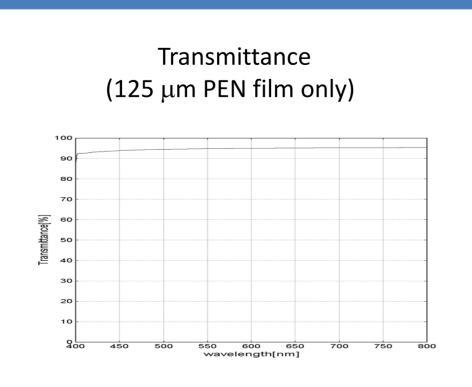




■ Two terminal in situ resistance measurement during bending test.

## **Results – Optical Transmittance**

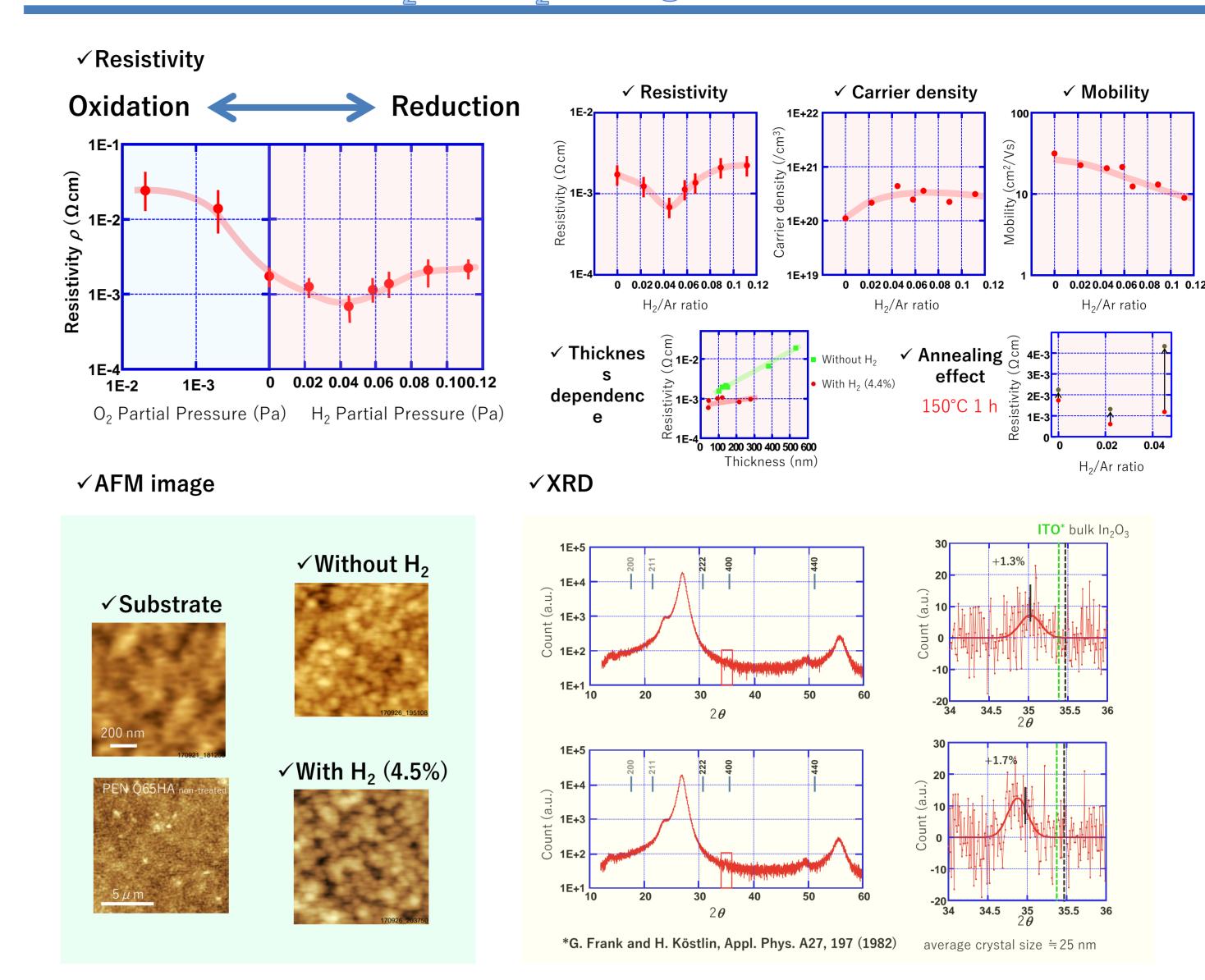




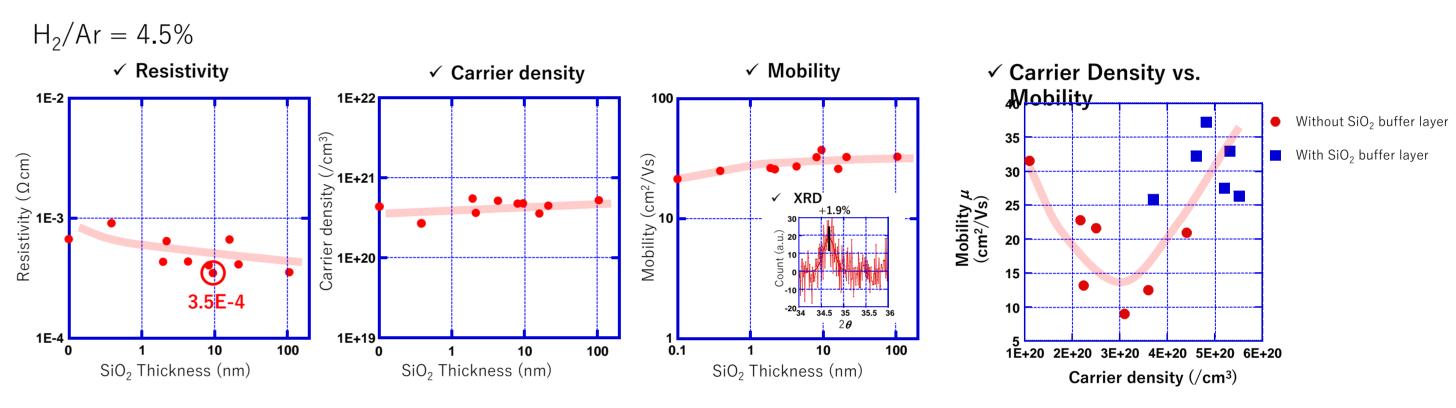
## Take Home Messages

- Hydrogen addition and SiO<sub>2</sub> buffer layer insertion are effective for lowering resistivity of ITO films on the plastic substrate formed by RF-magnetron sputtering.
- There are two increase mechanisms in resistivity due to bending: deterioration in resistivity due to the number of bending cycles and a reversible change due to one bending.
- Optical microscopy revealed that the increase in resistance was caused by cracks in the film.

### Results – Effect of H<sub>2</sub> and O<sub>2</sub> mixing



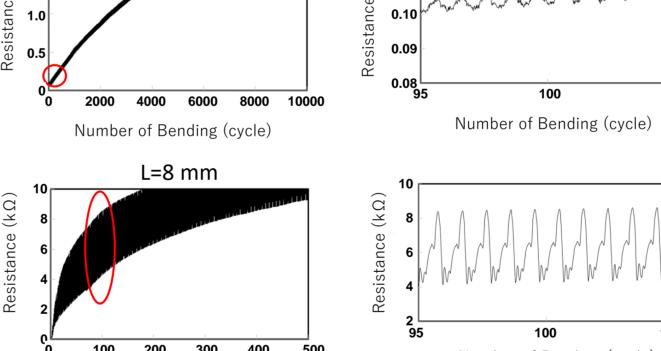
### Results – Effect of SiO<sub>2</sub> buffer layer



### **Bending Test**

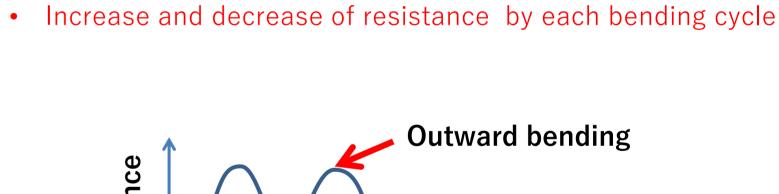
✓ Resistance change by bending

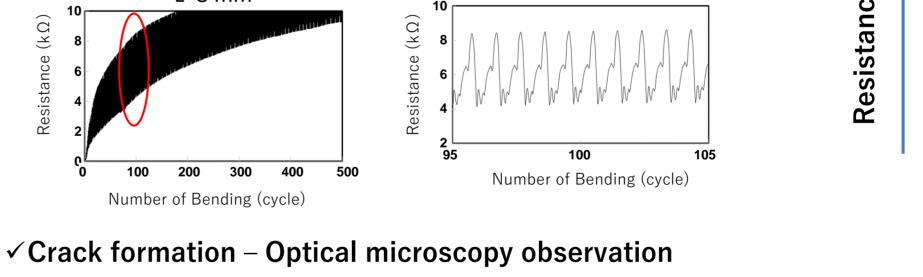
#### L=16 mm Resistance change has two part Slow rise in resistance due to the number of bends and a series of the series of

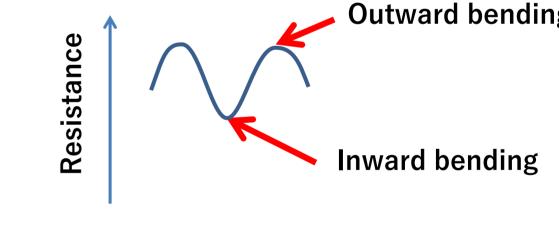


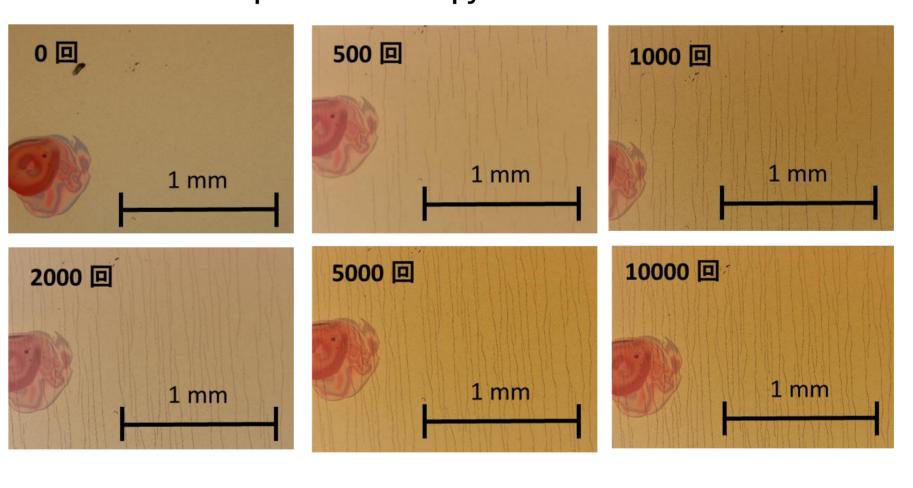
✓ Resistance change – Hall measurement during bending

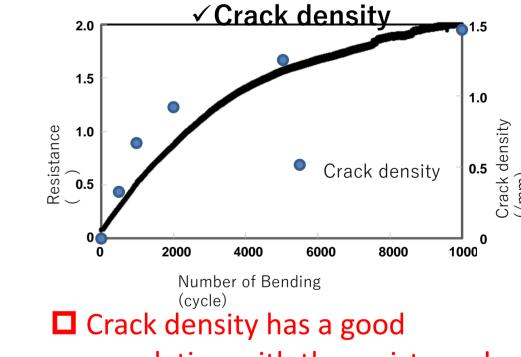
parallel





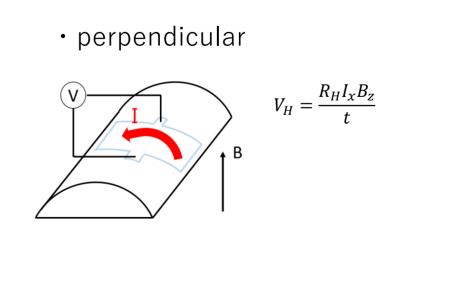


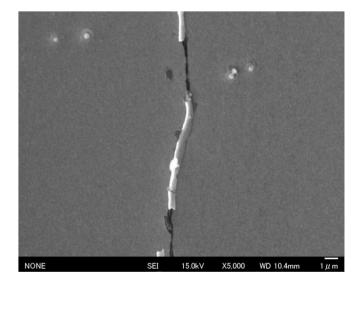


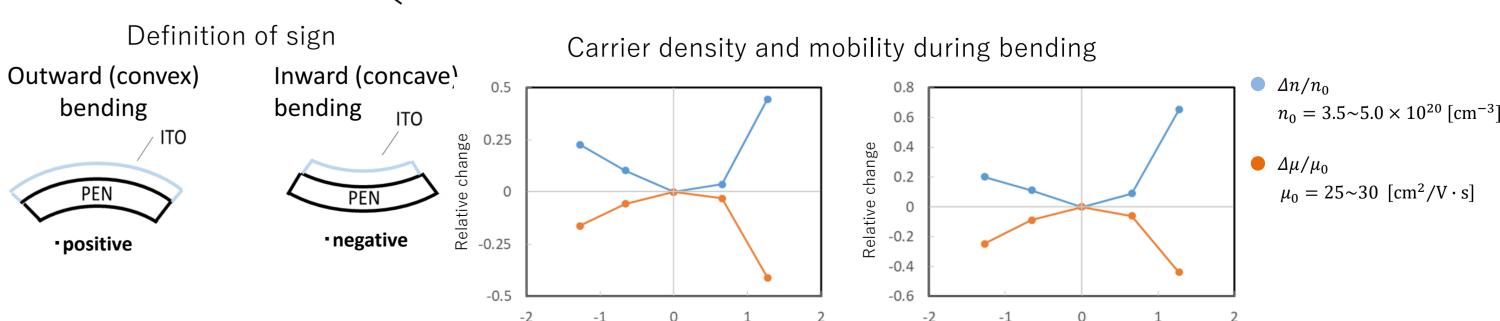


correlation with the resistance!

✓ SEM observation of individual crack







☐ Carrier density increased and mobility decreased in ether bending directions!

- reversible rise and fall of resistance in one cycle is due to the rise in carrier density and the decrease in mobility by bending.
- Durability due to bending has a critical value, and a strain of about 1% or more shortens the life of the ITO thin film.

Thank you for your kind attention